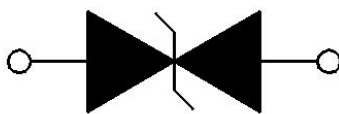
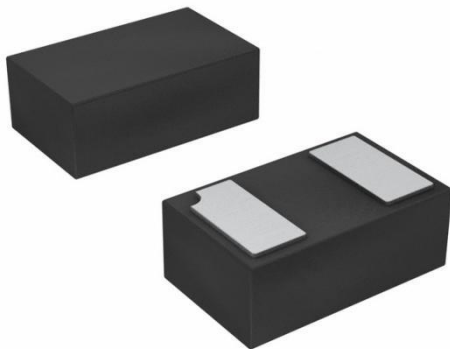


Features

- 2-pin lead-less package
- Junction capacitance (Max value: 20pF)
- Peak Pulse Current (8/20μs):5A
- IEC61000-4-2 (ESD) ±20kV (air), ±15kV (contact)
- Low clamping voltage
- Low leakage current
- Working voltages:24V
- RoHS Compliant

Appearance & Symbol



Bi-directional

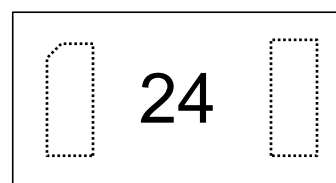
Mechanical Characteristics

- Package: DFN1006
- Lead Finish:Matte Tin
- Case Material: “Green” Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Tape Reel :10000pcs

Applications

- Cellular Handsets and Accessories
- Personal Digital Assistants
- Notebooks and Handhelds
- Portable Instrumentation,Digital Cameras
- Peripherals, Audio Players, Industrial Equipment

Marking Information



24=Marking Code

Absolute Maximum Ratings (T=25°C, RH=45%-75%, unless otherwise noted)

Parameters	Symbol	Value	Unit
Peak Pulse Power (tp=8/20μs waveform)	P _{PP}	300	W
Peak Pulse Current (8/20μs)	I _{PP}	5	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	±20 ±15	KV
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

Electrical Characteristics (T=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V _{RWM}				24	V
Reverse Breakdown Voltage	V _{BR}	I _R = 1mA	27		31	V
Reverse Leakage Current	I _R	V _R = 24V			0.2	uA
Clamping voltage	V _C	I _{PP} = 1A, T _p =8/20us			40	V
Clamping voltage	V _C	I _{PP} = 5A, T _p =8/20us			60	V
Junction capacitance	C _J	V _R =0V, f =1MHz			20	pF

Typical Characteristics

FIG1: Power rating derating curve

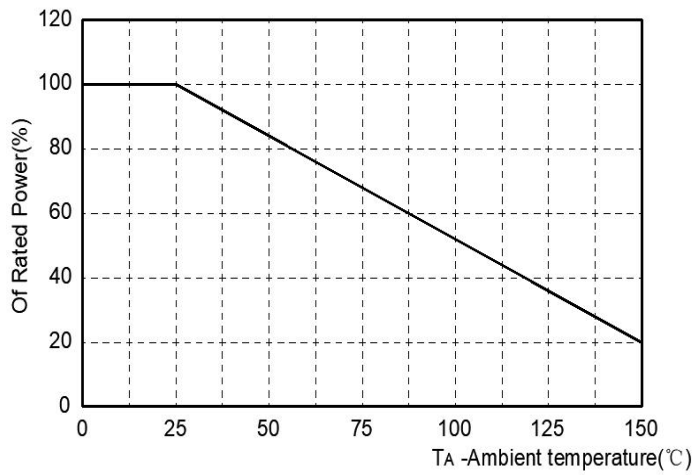


FIG2: pulse Waveform

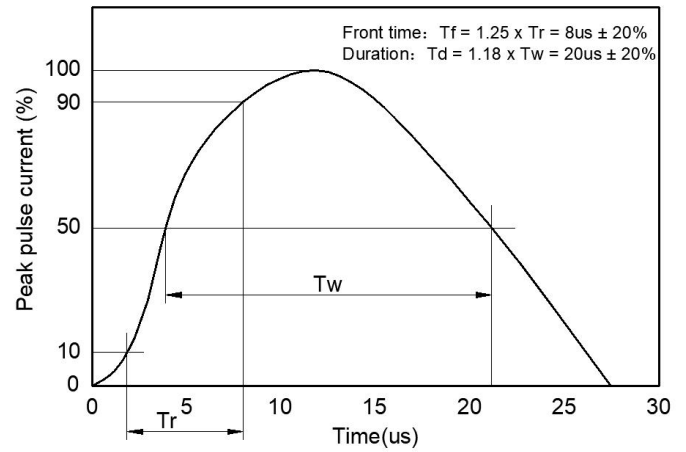


FIG3: Capacitance between terminals characteristics

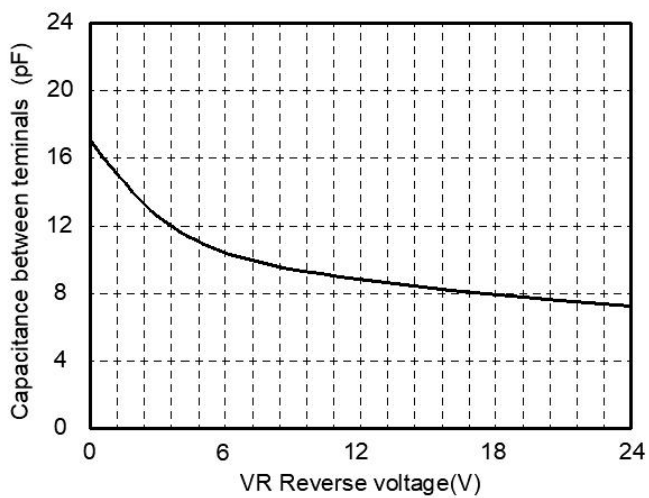
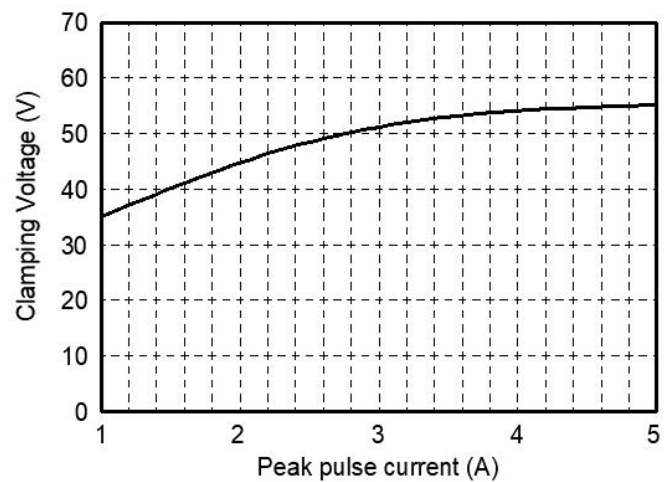


FIG4: Clamping Voltage vs. Peak Pulse Current

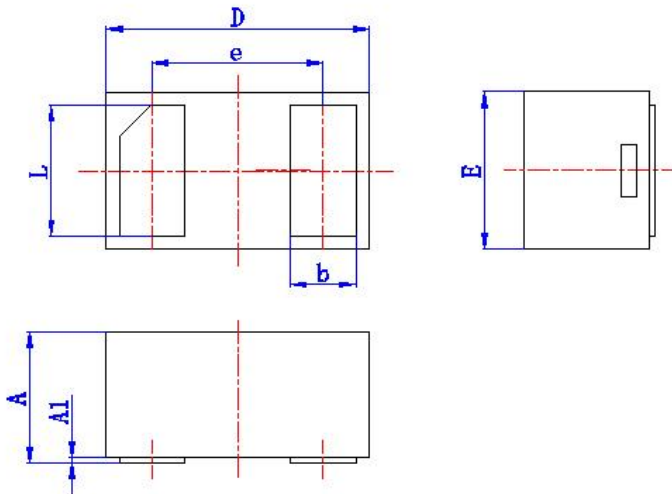


Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C

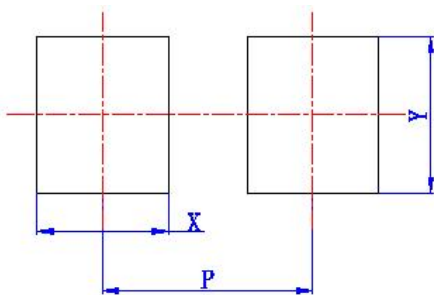


Package mechanical data



Symbol	Dimension in Millimeters	
	min	max
A	0.4	0.52
A1	0	0.05
D	0.9	1.1
E	0.55	0.65
e	(0.65)	
b	0.18	0.32
L	0.34	0.55

Suggested Land Pattern



Symbol	Dimension in Millimeters
	typ
X	(0.5)
Y	(0.7)
P	(0.8)